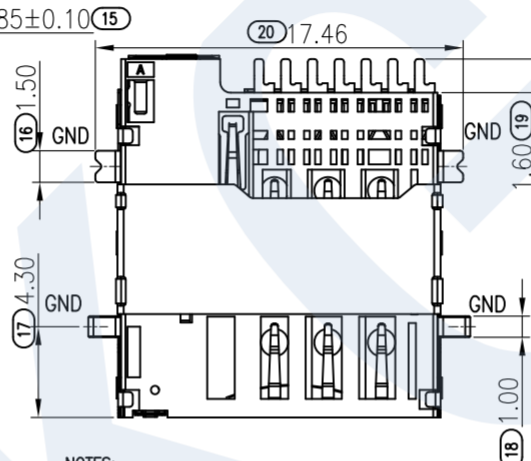
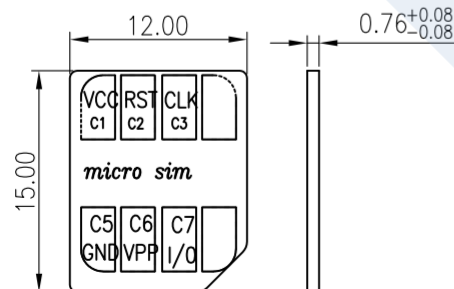


[illegible]

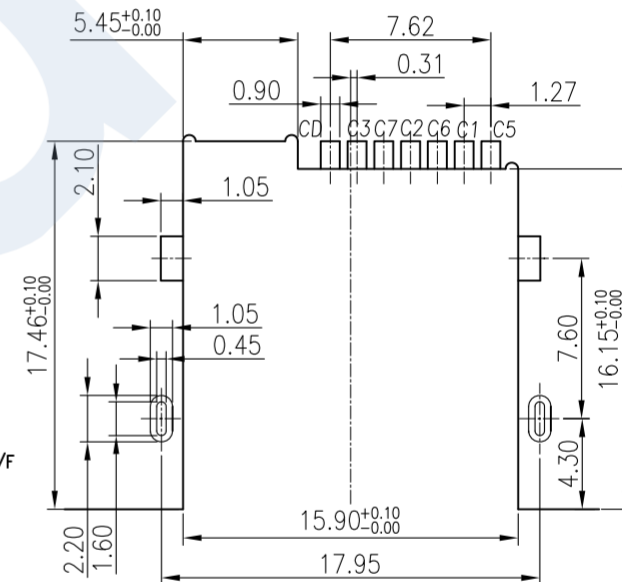
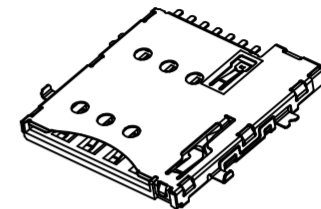
Insulator: High Temperature Thermoplastic, UL 94V-0.
Contact: Copper Alloy
Shell: STAINLESS

Contact: Plated 30u" Ni Overall ,Solder Area: Tin,Contact G/F
Shell: Plated 30u" Ni Overall
Plated G/F Selective Contact Area

Current Rating :0.5mA max.
Voltage Rating :50V DC MAX
Ambient Temperature Range :-20°C~+85°C
Storage Temperature Range :-40°C~+70°C
Ambient Humidity Range :95% R.H. Max.
Contact Resistance:100mΩ max.
Insulation Resistance:1000MΩ min./250V DC
Dielectric Withstanding Voltage:500V AC
Mating Cycles:5,000 Insertions
Temperature:260°C ±5°





SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



RECOMMENDED PCB LAYOUT

GENERAL TOLERANCE ± 0.05

MILLIMETERS	INCH	UNITS				
		MM				
X° ± 2°	X° ±	MAT'L	PART NUMBER:	TITLE: MICRO-SIM PUSH/PUSH 6PIN 1.35H 帶CD PIN (有彈片) 反沉1.1		
.X ± 0.30	.XX ±	SEE NOTES				
.XX ± 0.20	.XXX ±	FINISH	APPD:	DWG NO.:		
.XXX± 0.10	.XXXX±	SEE NOTES				
		QTY	CHKD:			
		SEE NOTES	DR:			
				1:1	1/2	AO